

09/462,214

ABSTRACT

An adhesive for semiconductor parts, comprising, as a base polymer, at least one cyclic structure-containing thermoplastic polymer selected from the group consisting of (a) a cycloolefin polymer and (b) an aromatic-condensed polymer having a repeating unit of an aromatic ring in its main chain, and having a number average molecular weight of 1,000 to 500,000, an adhesive sheet formed of the adhesive, a semiconductor part package making use of the adhesive, and a production process of the package.